(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
7 July 2005 (07.07.2005)

PCT

(10) International Publication Number
WO 2005/062375 A1

(51) International Patent Classification[7]: H01L 21/68

(21) International Application Number:
PCT/KR2004/003339

(22) International Filing Date:
17 December 2004 (17.12.2004)

(25) Filing Language: Korean

(26) Publication Language: English

(30) Priority Data:
10-2003-0094757
22 December 2003 (22.12.2003) KR

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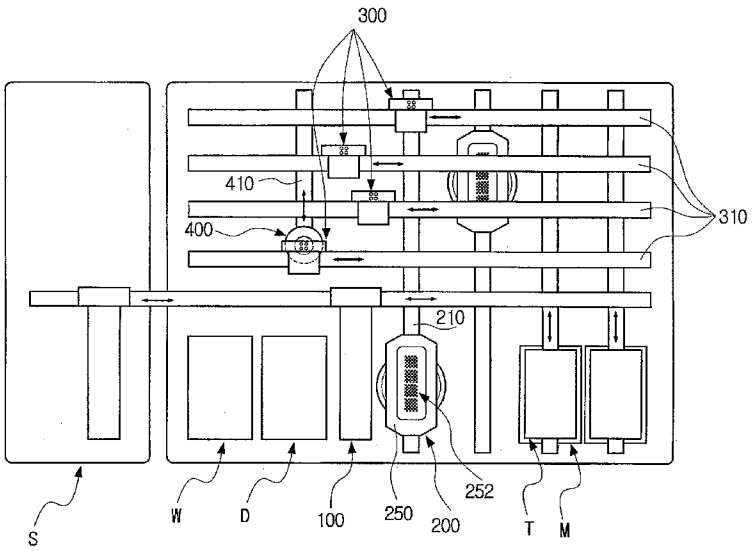
(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*

[Continued on next page]

(54) Title: TRANSFER MECHANISM AND TRANSFER METHOD OF SEMICONDUCTOR PACKAGE



(57) Abstract: Disclosed are a semiconductor package transfer mechanism and a semiconductor package transfer method. The semiconductor package transfer mechanism includes a plurality of pickup units, which are movable along a shaft extending in one direction and operated individually from each other, and a vision inspection apparatus installed across a moving route of the pickup unit in order to inspect defects of the semiconductor packages transferred thereto by means of the pickup units. The pickup units pick up a predetermined amount of semiconductor packages adapted for one-time photographing capacity of the vision inspection apparatus and instantly transfer the semiconductor packages to the vision inspection apparatus. Time delay and waiting time for the semiconductor packages are significantly reduced during the process of the handler system, thereby significantly improving the transfer efficiency and vision inspection efficiency.

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